



## PCN / EOL Notification

**Product Change Notification Number: SC080405**

**Date\*:** January 29, 2008

**Title:** 1M DataFlash Die Shrink

**Product Identification:**

AT45DB011B - All packages

Please refer to Appendix A for a complete list of part numbers.

**Reason for Change:**

Design

Manufacturing Location

Processing

Quality/Reliability

Logistics

Material

**Change Description:**

The Atmel 1Mbit AT45DB011B DataFlash® has undergone a shrink from the 0.25um to the 0.13um CMOS process. The maximum operating frequency of the device has increased from 20MHz to 66MHz. With the die shrink, many new features and enhancements have been made. Please refer to the AT45DB011D data sheet for complete details. In addition Atmel is changing the lead plating material from 100% Matte-Tin to Nickel Palladium Gold (NiPdAu); both are RoHS compliant.

The low volume CBGA and TSSOP packages are no longer supported. For users of these packages, Atmel recommends the 8-lead, 150-mil SOIC or the 8-contact, 5mm x 6mm DFN package. A PCB change is required if migrating from the CBGA or TSSOP to the SOIC or DFN.

Please refer to the application notes in Appendix B.

**Identification Method to Distinguish Change:**

The new part numbers are:

AT45DB011D-MH

AT45DB011D-SH

AT45DB011D-SSH

Please refer to Appendix A for the complete list of part numbers.

**Qualification Data:**

available

will be available in WW

not applicable

**Samples:**

available

will be available in WW

not applicable

**Quantifiable Impact on Quality & Reliability:**

None

**Product Availability Date:**

January 22, 2008

**Last Time Buy Date:**

July 22, 2008

**Last Ship Date:**

January 22, 2009

\* All orders placed after the notification date are **non-cancellable** and **non-returnable (NCNR)**.

**Atmel Contact:** [pcnadm@atmel.com](mailto:pcnadm@atmel.com)

Atmel will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the Quality Contact e-mail address listed above.

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## Appendix A

EOL Part Number	Replacement Part Number	Specifications
New part number	AT45DB011D-SSH-B AT45DB011D-SSH-T	2.7V – 3.6V VCC 66MHz Fskc -40°C to 85 °C NiPdAu Lead Finish
AT45DB011B-SU AT45DB011B-SI AT45DB011B-SC AT45DB011B-SJ	AT45DB011D-SH-B AT45DB011D-SH-T	
New part number	AT45DB011D-MH-Y AT45DB011D-MH-T	
AT45DB011B-CC AT45DB011B-CI	Refer to Note 1	
AT45DB011B-XU AT45DB011B-XI AT45DB011B-XC	Refer to Note 1	

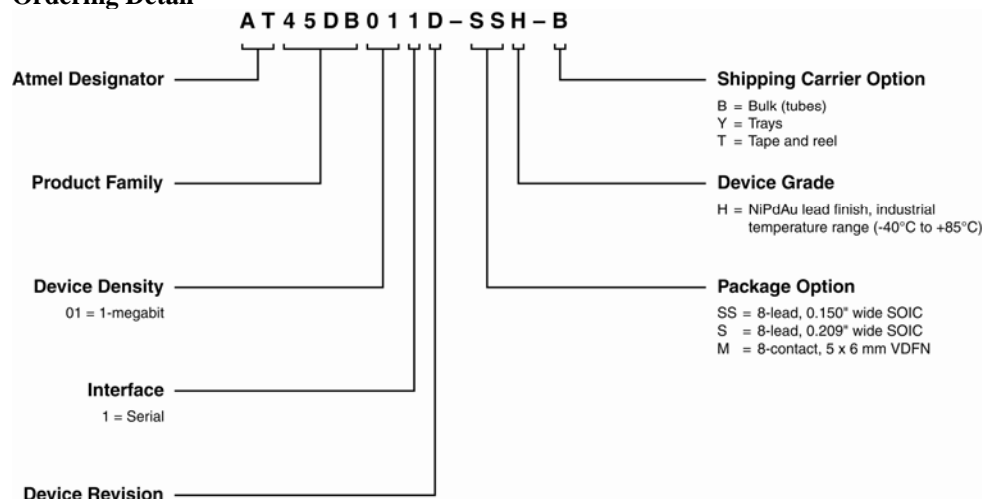
### Note 1:

- Please transition to the AT45DB011D-MH or AT45DB011D-SSH. See datasheet for package outline drawings.
- PCB change is required when changing package types.

### Note 2:

- B = Bulk Shipment in Tube
- T = Shipment with Tape and Reel
- Y = Bulk Shipment in Trays.

### Ordering Detail



## Appendix B



doc3644.pdf

Please refer to doc3644.pdf for the detail information regarding migration from the “B” to the “D” DataFlash Family”. You can also find [all application notes](#) from Atmel web site by holding the control key and click on this [link](#).